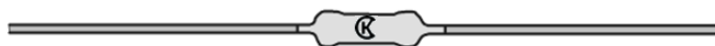


FEATURES

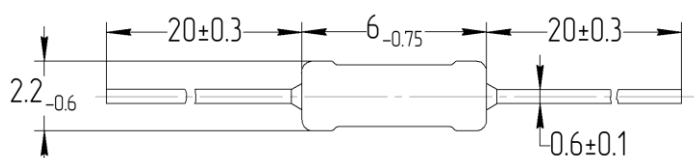
- 0.5% after 1000 h
- 2 % after 70000 h



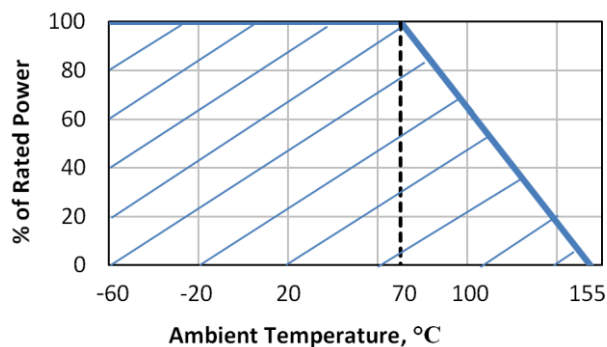
GENERAL SPECIFICATIONS

■ Operating Temp. Range:	-60 °C to 155 °C
■ Load Life 70 °C/ 1000 h:	for tol. 0.5 % 0.5 % for tol. 1 % 1 %
■ Max. Resistance Change at Rated Dissipation ΔR/R max. after 70000 h	2 %
■ Package:	Leaded
■ Process:	Metal Film
■ Substrate Material:	85 % Al ₂ O ₃
■ Coating:	Enamel
■ Termination Finish:	Sn-Pb

Size	Power (W)	Resistance Value, E192 Series (Ohms)	Resistance Tolerance (± %)	Max. Operating Voltage (V)	Temperature Coefficient (ppm/°C)
0207	0.125	10-98.8 100-2.21M	1, 0.5	200	±150 ±150, ±75



Dimensions in mm
Mass 0.15 g



PART NUMBER CODE

R1-129	1001	D	1
model	value	tolerance	TC
	10R0 = 10 Ω	D = 0.5 %	1 = 75 ppm
	2214 = 2.21 MΩ	F = 1 %	2 = 150 ppm

PERFORMANCE CHARACTERISTICS

Test	Condition	ΔR max.
Robustness of termination	IEC60115-1 (4.16)/ IEC 60068-2-21 Bending; Tensile	$\pm 0.5 \%$
Solderability	IEC60115-1 (4.17)/ IEC 60068-2-20 (235 \pm 5) °C; 2 s; solder bath method; SnPb40	Good tinning (>95 % covered, no visible damage)
Resistance to soldering heat	IEC60115-1 (4.18.2)/ IEC 60068-2-20 (260 \pm 5) °C; (10 \pm 1) s	$\pm 0.5 \%$; no visible damage
Rapid change of temperature	IEC60115-1 (4.19)/ IEC 60068-2-14 30 min at -60 °C; 30 min at 155 °C; 5 cycles	= tolerance
Vibration	IEC60115-1 (4.22)/ IEC 60068-2-6 32 sweep cycles per direction; 100 Hz to 2000 Hz; 2 mm; 200 m/s ²	$\pm 0.5 \%$
Low air pressure	IEC60115-1 (4.23.5)/ IEC 60068-2-13 67 Pa; 30 min; 15 °C to 35 °C	No visible damage
Damp heat, steady state	IEC60115-1 (4.24)/ IEC 60068-2-78 (40 \pm 2) °C; 56 days; (93 \pm 3) % RH	= tolerance

All tests are carried out in accordance with the following specifications:

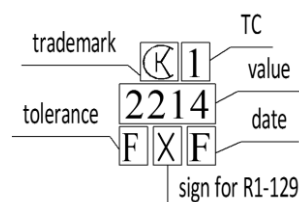
- IEC 60115-1 (clause),
- IEC 60068-2-xx (test method).

PACKAGING

Carton box.

MARKING

Nominal value (E24)	Marking
10 Ω to 98.8 Ω	10R0 to 98R8
100 Ω to 988 Ω	1000 to 9880
1 K Ω to 9.88 K Ω	1001 to 9881
10 K Ω to 98.8 K Ω	1002 to 9882
100 K Ω to 988 K Ω	1003 to 9883
1 M Ω to 2.21 M Ω	1004 to 2214



MOUNTING PROCEDURE

Can be used only in manual assembly techniques.

Date
2010 2011 2012 2013 2014 2015 2016 2017 2018 2019 2020 2021 2022 2023 2024 2025 2026 2027 2028 2029
A B C D E F H J K L M N P R S T U V W X